



## SMB1N-385V-02

- Ultraviolet High Power LED
- 385 nm, 1000 mW
- Zener diode
- AlInGaN chip, 1000 x 1000  $\mu\text{m}$
- PA9T SMD package
- Beam Angle: 20°



### Description



**SMB1N-385V-02** is a surface mount AlInGaN based high power ultraviolet LED, with a typical peak wavelength of 385 nm and optical output power of 1000 mW @ 700 mA. It comes in SMD package (PA9T) with **protection Zener diode**, silver plated soldering pads (lead free solderable), copper heat sink, and silicone resin molded lens.

### Maximum Ratings

Parameter	Symbol	Values		Unit
		Min.	Max.	
Power Dissipation	$P_D$		2800	mW
Forward Current	$I_F$		700	mA
Pulse Forward Current *	$I_{FP}$		1000	mA
Reverse Voltage	$V_F$		**	V
Thermal Resistance	$R_{THJA}$		10	K/W
Junction Temperature	$T_J$		120	°C
Operating Temperature	$T_{CASE}$	- 40	+ 100	°C
Storage Temperature	$T_{STG}$	- 40	+ 100	°C
Lead Solder Temperature (max. 5s)	$T_{SLD}$		+ 250	°C

\* duty cycle = 1 %, pulse width = 10  $\mu\text{s}$  \*\* not designed for reverse operation

### Electro-Optical Characteristics ( $T_{CASE} = 25^\circ\text{C}$ )

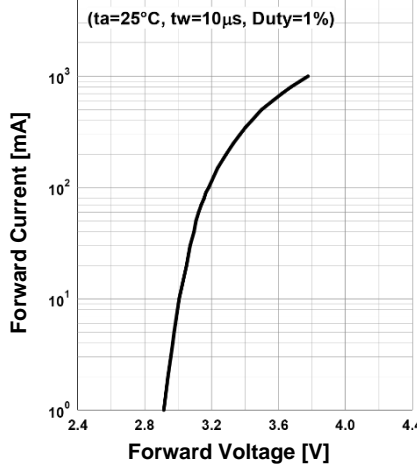
Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Peak Wavelength	$\lambda_P$	$I_F=500\text{ mA}$	380		390	nm
Half Width	$\lambda_{\Delta}$	$I_F=500\text{ mA}$		12		nm
Forward Voltage	$V_F$	$I_F=500\text{ mA}$		3.5	3.9	V
	$V_{FP}$	$I_{FP}=1\text{ A}^*$		3.8		
Total Radiated Power	$P_O$	$I_F=500\text{ mA}$		1000		mW
		$I_{FP}=1\text{ A}^*$		1800		
Radiant Intensity	$I_E$	$I_F=500\text{ mA}$		3300		mW/sr
		$I_{FP}=2\text{ A}^*$		6100		
Beam Angle	$2\theta_{1/2}$	$I_F=100\text{ mA}$		10		deg.
Rise Time	$t_r$	$I_F=500\text{ mA}$		40		ns
Fall Time	$t_f$	$I_F=500\text{ mA}$		100		ns

\* duty cycle = 1 %, pulse width = 10  $\mu\text{s}$

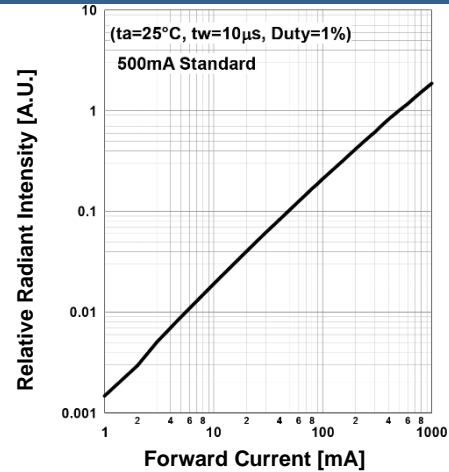


## Typical Performance Curves

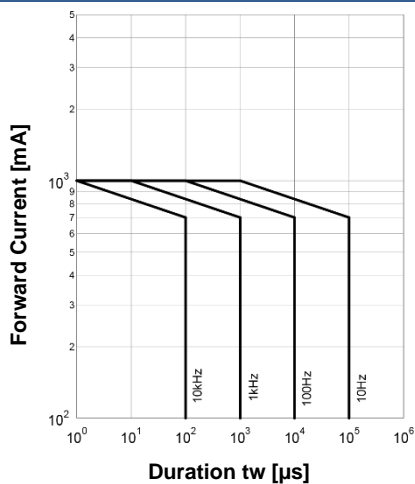
### Forward Current vs. Forward Voltage



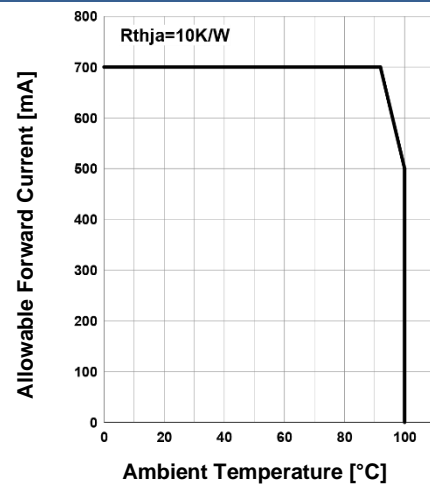
### Relative Radiant Intensity vs. Forward Current



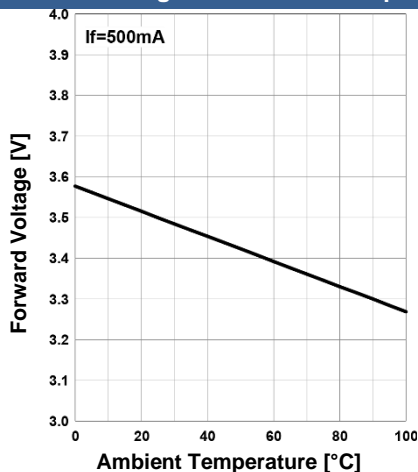
### Forward Current vs. Pulse Duration



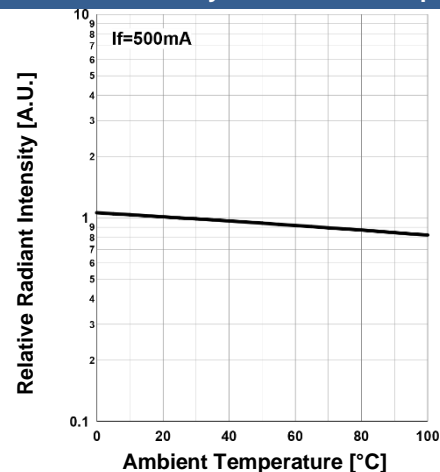
### Allowed Forward Current vs. Amb. Temperature



### Forward Voltage vs. Ambient Temperature



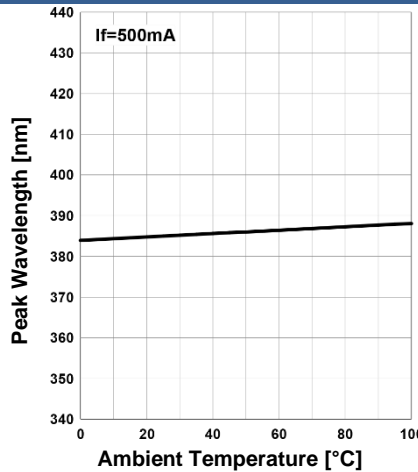
### Rel. Radiant Intensity vs. Ambient Temperature



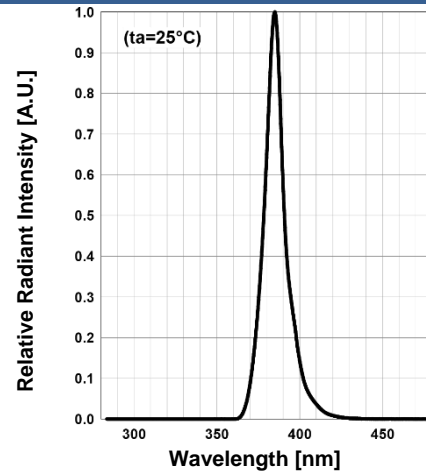


## Typical Performance Curves

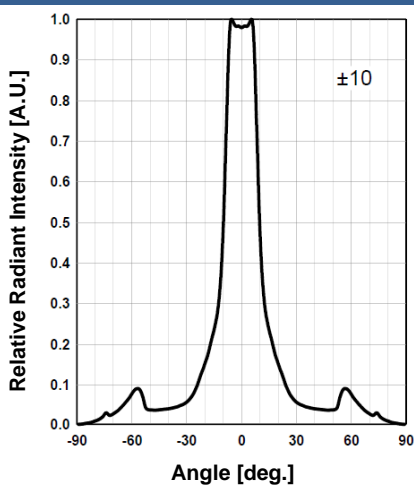
Peak Wavelength vs. Amb. Temp.



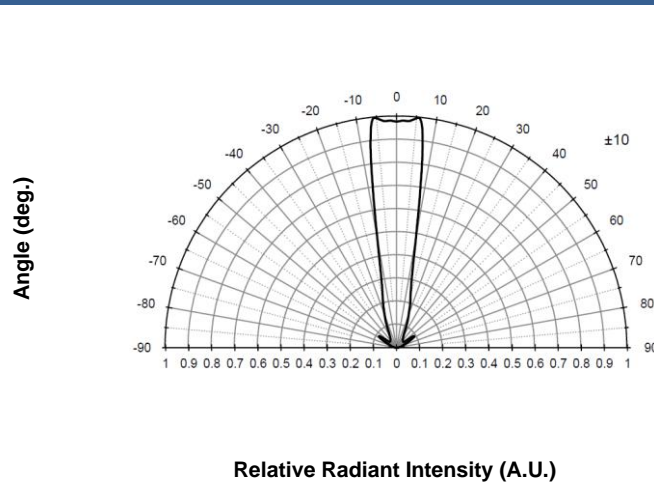
Relative Spectral Emission



Radiation Characteristics

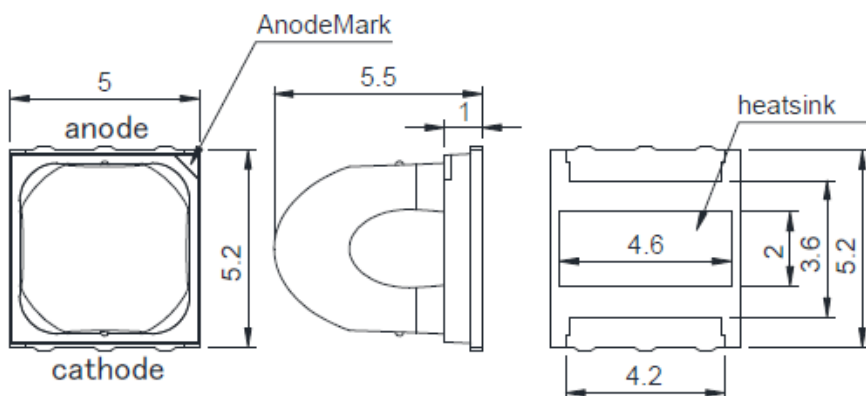


Radiation Characteristics

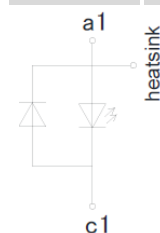


## Outline Dimensions

### PA9T



Lead	Function
Pin a1	Anode
Pin c1	Cathode



all dimensions in mm

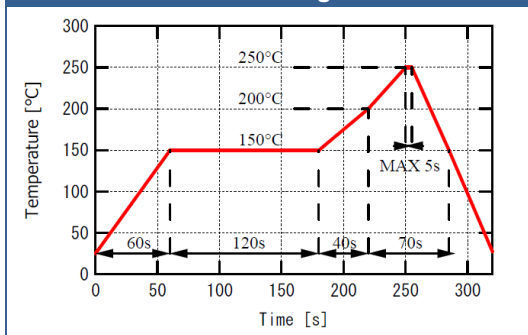


## Precautions

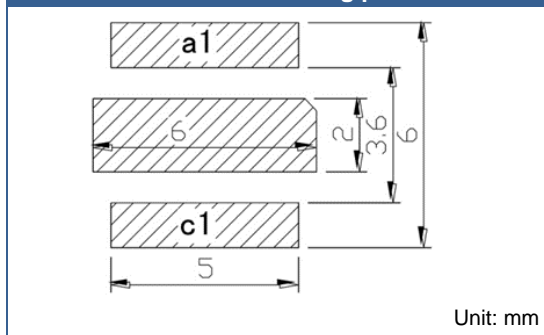
### Soldering

- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering

Recommended soldering conditions



Recommended soldering patterns



### Cleaning

**Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended**

DO NOT USE acetone, chloroform, trichloroethylene, or MKS

DO NOT USE ultrasonic cleaners

### Static Electricity

**LEDs are sensitive to electrostatic discharge (ESD).** Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

### Radiation

During operation these LEDs do emit light, which **could be hazardous to skin and eyes**, and **may cause cancer**. Do avoid exposure to the emitted light. Protective glasses if needed. It is further advised to attach a warning label on products/systems.

### Operation

**Do only operate LEDs with a current source.**

Running these LEDs from a voltage source will result in complete failure of the device.

Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.